

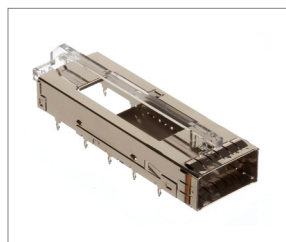
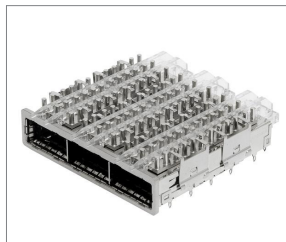
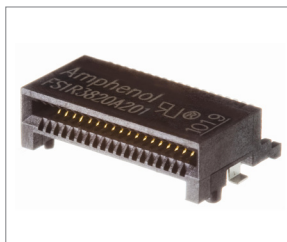
eQSFP

Product Description

The eQSFP interconnect system is comprised of a 38 position 0.8mm pitch SMT connector, and a press-fit cage. With four channels of data in one pluggable, the system interface is capable of transferring data up to 28 Gbps/Channel, and replacing up to 4 standard SFP+ receptacles. These features result in greater port density and overall cost savings over traditional SFP+ products. Supporting standards include, Gigabit Ethernet, InfiniBand, and SONET/SDH with different data rate options. eQSFP includes cages in single and ganged configurations with multiple heat sink options supporting various thermal requirements and port status with light pipes options.

Applications		SFF Supported Standards	
Data Servers	SAN, NIC cards	eQSFP	
Router/Switches	HBA'S	Connector SFF-8672	
Hubs		Cage SFF-8683	

Product Specifications - ExpressPort® QSFP+			
CONNECTOR		CAGE	
Materials Specifications			
Housing	Black color, Glass reinforced, Lead Free Solder Reflow Process Compatible Thermo Plastic	PCB Thickness	1.44 mm MIN for single mounted. (1xN)
Contacts Base Material	Phosphor Bronze	Belly to Belly	2.85 mm MIN for 1xN.
Contact Normal Force	50 g Min		
Plating Solder Tails	Matte tin		
Plating Mating Area	Gold		
Resonance Dampening Feature	Conductive Polymer		
Operating & Storage Temperature	-40° to +85° C		
Electrical Specifications			
Operating Voltage	30 VDC per contact		
Operating Current	0.5 A per contact		
Differential Impedance	100 Ω +/-10 Ω		
Mechanical Specifications			
Mating Force	40 N Maximum	Unmating Force	30 N Maximum
Durability	250 mating cycles	Insertion Force to PCB	780 N for 1 port 1000 N for 2 Ports 1700 N for 4 Ports 2400 N for 6 Ports
Options			
Packaging	Tape and Reel	Packaging	Tray
EMI Options	Gasket, Spring Fingers		
Cage Mounting	Behind Bezel, Thru Bezel, Hybrid		
Configurations	1XN (N=1,2,3,4,6)		
Environmental Specifications			
RoHS	Yes		
Halogen Free	Yes		
Flammability Rating	UL 94V-0		



Ordering Information

eQSFP Series

FS1 M 38 X 0 00 00

FS1	SERIES DESIGNATION	
M	STYLE M - 100 Ohm	
38	NUMBER OF POSITIONS 38 - 38 Positions	
X	PLATING 2 - 30 μ" (0.76 μm) Gold over 100 μ" (2.54 μm) min of Matte Tin on Solder Termination, 50 μ" (1.27 μm) - 75 μ" (1.91 μm) of Nickel Under Plate All Over 3 - 15 μ" (0.38 μm) Gold over 100 μ" (2.54 μm) min of Matte Tin on Solder Termination, 50 μ" (1.27 μm) - 75 μ" (1.91 μm) of Nickel Under Plate All Over	
	SPECIAL OPTION 00 - QSFP+ Connector No Shorting Bars, No Hold Down Tabs	00
	OPTION 1 00 - Standard ME - New Connector	00
	KEYING 0 - No Key	0



Order Information:

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 For more information consult factory or visit amphenol-highspeed.com

Product Applications; List represents common uses for the product but is not limited to these uses.
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